

Minebea Power Semiconductor Device Inc.

## **Six-input Type Single Chip Inverter IC**

### **Application Note**

**【Rev. 1】**

#### **Types**

|                       |                 |
|-----------------------|-----------------|
| <b>200V AC system</b> | <b>ECN30626</b> |
|-----------------------|-----------------|

Minebea Power Semiconductor Device Inc.  
Design Development Division

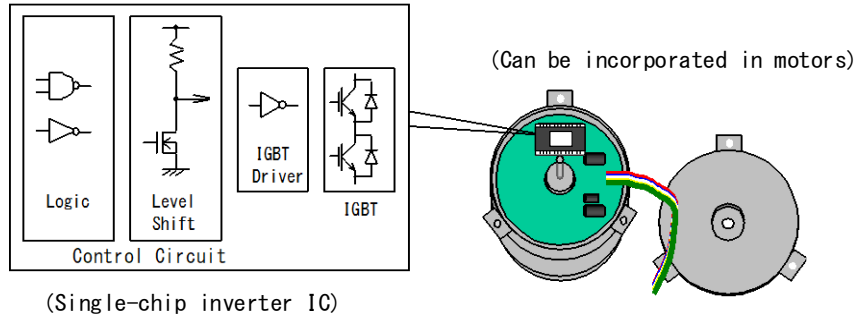
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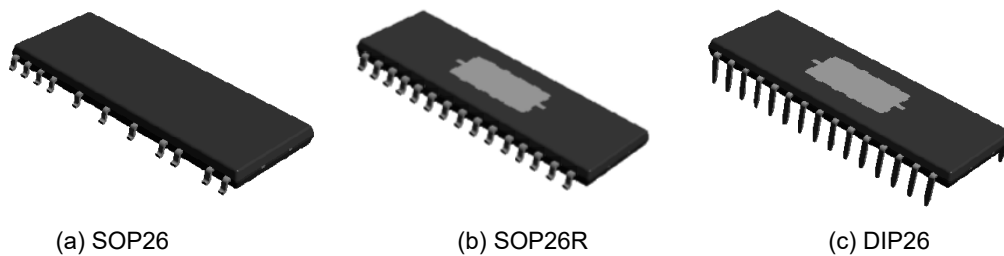
## 1. Outline

### 1.1 Single Chip Inverter IC Outline

Our single chip inverter ICs are monolithic ICs integrating various constituent devices and circuits required for inverter control on a single chip. They are for driving motors, suited for variable speed control of three-phase induction motors and brushless DC motors. The advantage of downsizing by the use of a single chip structure can be used to reduce the control board in size, which can be incorporated in a motor.



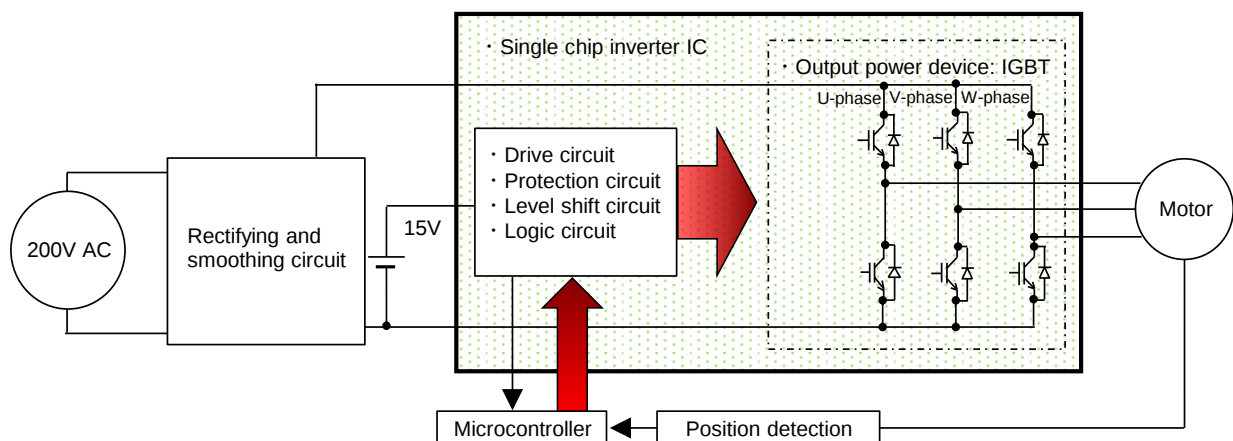
**FIGURE 1.1.1 Image of Motor with Built-in Control Board**



**FIGURE 1.1.2 Types and Packages of IC**

### 1.2 System Configuration

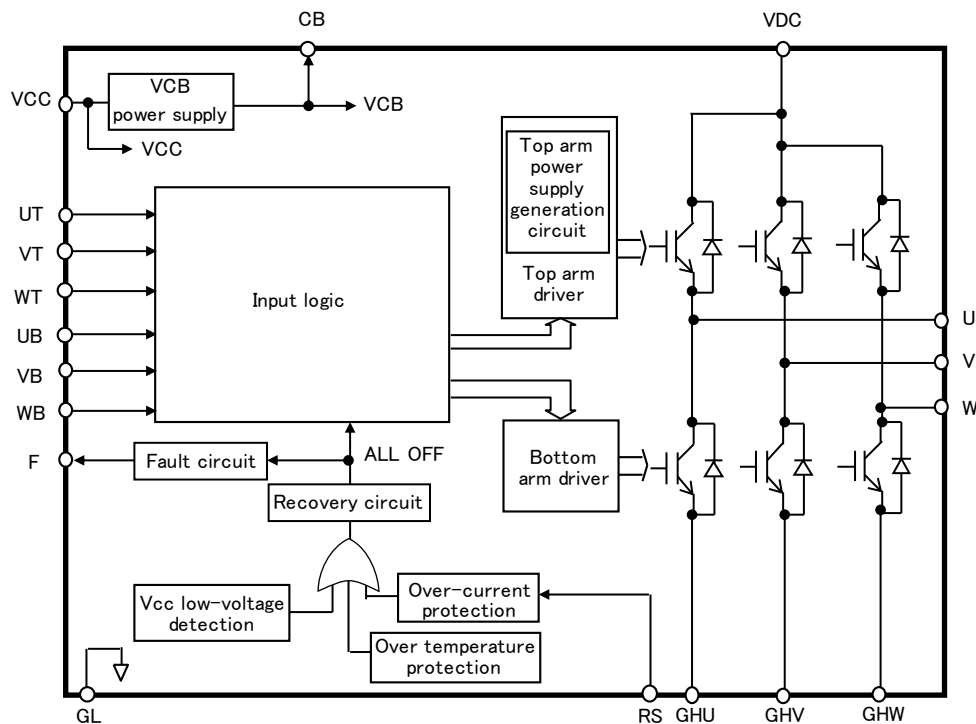
An inverter is a device that converts DC currents into AC. It can be used to drive motors with efficient variable-speed control. Figure 1.2.1 shows the example of basic system configuration of an inverter IC. To drive the three-phase motor with an inverter, six IGBTs and free wheel diodes are used as output stages. The IC consists of an IGBT driving power circuit, level shift circuit, a logic circuit and other components. Our Inverter ICs can directly receive high voltage supplied from rectifying commercial AC power, because they have high dielectric strength. This obviates the need of a step-down circuit, thus inhibiting efficiency cuts induced by voltage conversion.



**FIGURE 1.2.1 Example of Basic System Configuration**

### 1.3 Block Diagram of IC

Figure 1.3.1 shows a block diagram.



**FIGURE 1.3.1 Block Diagram of IC**

## 2. Content of Specifications

The following items have been described in the specifications.

### (1) Maximum ratings

- It describes direct conditions (electric, thermal use conditions) leading to IC destruction, and so on. And the safety operating range with operating conditions is shown by minimum or maximum value.
- In a case the specified values shown in each item are exceeded, products may be damaged or destroyed even for a moment. These specified values should never be exceeded under any operating conditions.

### (2) Electrical characteristics

- It provides for electric characteristics of the IC, and describes minimum, standard, and maximum.

### (3) Function and operation

- It describes Truth Table, Timing Chart, Protection Function, and so on.

### (4) Standard application

- It describes circuit examples and external components to operate IC.

### (5) SOA and deratings

- It describes Safe Operation Area (SOA), deratings, and so on.

### (6) Pin assignments and pin definitions

- It describes pin assignments, pin names and pin definitions.

### (7) Inspection

- It describes inspection conditions.

### (8) Important notice, precautions

- It describes notes of the static electricity, the maximum rating, handling, and so on.

### (9) Appendix and reference data

- It describes packaging and dimensions.

### 3. Specifications

#### 3.1 IC Types

Table 3.1.1 shows ratings, package types, and mounting types of the ICs.

**TABLE 3.1.1 IC and Package Types**

| No. | Type      | Maximum ratings                                                                                   | Package type | Mounting type      |
|-----|-----------|---------------------------------------------------------------------------------------------------|--------------|--------------------|
| 1   | ECN30626F | Output device withstand voltage : 600V<br>Output current (Pulse) : 3A<br>Output current (DC) : 2A | SOP26        | Surface mount type |
| 2   | ECN30626R |                                                                                                   | SOP26R       | Surface mount type |
| 3   | ECN30626P |                                                                                                   | DIP26        | Pin insertion type |

## 3.2 Pin Assignments

Table 3.2.1 shows pin assignments of ECN30626F, ECN30626R and ECN30626P.

**TABLE 3.2.1 Pin Assignments(ECN30626F, ECN30626R, ECN30626P)**

| Pin No.                 | Symbol | Pin functions                                                          | Remarks |
|-------------------------|--------|------------------------------------------------------------------------|---------|
| 1,2,3,18<br>19,20,23,24 | NC     | No connection                                                          | Note 2  |
| 4                       | VDC    | High voltage power supply                                              | Note 1  |
| 5                       | W      | W-phase output                                                         | Note 1  |
| 6                       | V      | V-phase output                                                         | Note 1  |
| 7                       | U      | U-phase output                                                         | Note 1  |
| 8                       | GHW    | Emitter of W-phase bottom arm IGBT and anode of W-phase bottom arm FWD |         |
| 9                       | GHV    | Emitter of V-phase bottom arm IGBT and anode of V-phase bottom arm FWD |         |
| 10                      | GHU    | Emitter of U-phase bottom arm IGBT and anode of U-phase bottom arm FWD |         |
| 11                      | RS     | Input for over-current protection                                      |         |
| 12                      | UB     | Input control signal for U-phase bottom arm                            |         |
| 13                      | VB     | Input control signal for V-phase bottom arm                            |         |
| 14                      | WB     | Input control signal for W-phase bottom arm                            |         |
| 15                      | UT     | Input control signal for U-phase top arm                               |         |
| 16                      | VT     | Input control signal for V-phase top arm                               |         |
| 17                      | WT     | Input control signal for W-phase top arm                               |         |
| 21                      | F      | Fault signal output                                                    |         |
| 22                      | CB     | VCB power supply output                                                |         |
| 25                      | VCC    | Control power supply                                                   |         |
| 26                      | GL     | Ground                                                                 |         |

Note 1. High voltage pin.

Note 2. Not connected to the chip in the IC.

Note 3. The tab potential is the same as that of the GL pin. Set the tab potential to open or the same as that of GND. If the tab is mounted on the external cabinet of the motor for heat radiation purposes, the IC will not be able to withstand an insulation withstand voltage test in which a high voltage is applied between the external cabinet and the GND. Please insert an insulation sheet or something similar between the IC tab and the external cabinet.

## 3.3 Functions of Pins

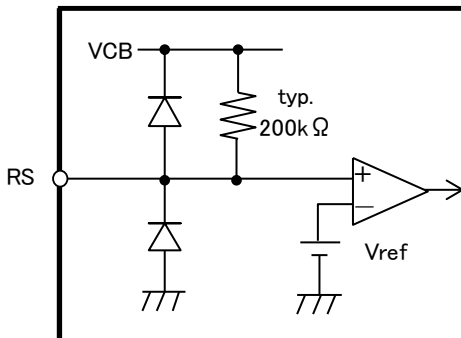
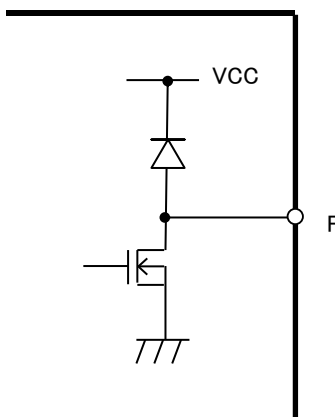
**TABLE 3.3.1 List of Pins and Functions (1/2)**

| No. | Pin                              | Pin functions                                                                  | Functions and Precautions                                                                                                                                                                                                                                                                                                                                                                                                                                                                 | Related items                                                                                                                                                    | Remarks          |
|-----|----------------------------------|--------------------------------------------------------------------------------|-------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|------------------------------------------------------------------------------------------------------------------------------------------------------------------|------------------|
| 1   | VCC                              | Control power supply                                                           | <ul style="list-style-type: none"> <li>• Powers the drive circuits for the top and bottom arms, the built-in VCB supply circuit, and others.</li> <li>• Determine the capacity of the power supply for Vcc allowing for a margin determined by adding the current taken out of the CB pin to the standby current ICC.</li> </ul>                                                                                                                                                          | <ul style="list-style-type: none"> <li>• 3.5.1 (1)<br/>Vcc low-voltage detection</li> <li>• 5.1 to 5.6<br/>Inverter IC destruction by surge or noise.</li> </ul> | —                |
| 2   | VDC                              | High voltage power supply                                                      | <ul style="list-style-type: none"> <li>• Connected to the collectors of the top arm IGBTs.</li> </ul>                                                                                                                                                                                                                                                                                                                                                                                     | <ul style="list-style-type: none"> <li>• 5.1 to 5.4, 5.7<br/>Inverter IC destruction by surge or noise.</li> </ul>                                               | High voltage pin |
| 3   | CB                               | VCB power supply output                                                        | <ul style="list-style-type: none"> <li>• Outputs a voltage (typ. 5.0V) generated in the built-in VCB power supply.</li> <li>• VCB supply powers the IC internal circuits (input buffer, over-current protection and others) and can be used as a power supply for external circuits such as MCU, Hall elements, and so on.</li> <li>• Connect an oscillation prevention capacitor C0 (1.0μF ±10% recommended) to the CB pin.</li> </ul>                                                   | <ul style="list-style-type: none"> <li>• 3.5.4 VCB power supply</li> </ul>                                                                                       | —                |
| 4   | GL                               | Ground                                                                         | <ul style="list-style-type: none"> <li>• It is the ground pin for Vcc and VCB power lines.</li> </ul>                                                                                                                                                                                                                                                                                                                                                                                     | —                                                                                                                                                                | —                |
| 5   | GHU<br>GHV<br>GHW                | Emitter of U/V/W-phase bottom arm IGBT and anode of U/V/W-phase bottom arm FWD | <ul style="list-style-type: none"> <li>• The GHU, GHV and GHW pins are connected to the emitters of the U-phase, V-phase and W-phase bottom arm IGBTs respectively.</li> <li>• The current in each phase can be detected by connecting a shunt resistor Rs between these pins (GHU, GHV, GHW) and the GL pin.</li> <li>• DC current can be detected by connecting the GHU, GHV and GHW pins all together and connecting a shunt resistor Rs between the RS pin and the GL pin.</li> </ul> | <ul style="list-style-type: none"> <li>• 3.5.1 (2)<br/>Setting method for over-current protection</li> </ul>                                                     | —                |
| 6   | U<br>V<br>W                      | U/V/W-phase output                                                             | <ul style="list-style-type: none"> <li>• These are outputs of a three-phase bridge consisting of six IGBTs and free wheel diodes.</li> </ul>                                                                                                                                                                                                                                                                                                                                              | —                                                                                                                                                                | High voltage pin |
| 7   | UT<br>VT<br>WT<br>UB<br>VB<br>WB | Input control signal for U/V/W-phase top/bottom arm                            | <ul style="list-style-type: none"> <li>• Inputs control signals of each phase.</li> <li>• When inputting "H", the IGBTs turn on. When inputting "L", the IGBTs turn off.</li> <li>• U, V and W stand for each phase. T and B stand for top arm and bottom arm respectively.</li> <li>• If the switching noise is monitored, mount a capacitor.</li> <li>• The maximum rating of input voltage is VCB+0.5V.</li> </ul>                                                                     | —                                                                                                                                                                | —                |

The diagram illustrates the internal equivalent circuit for the input pins UT, VT, WT, UB, VB, and WB. A common input bus is shown on the left. This bus connects to three parallel branches: a pull-down resistor (labeled 'typ. 200kΩ') to ground, a diode connected to the VCB supply line, and an IGBT with a parallel diode connected to ground. The IGBT's emitter is grounded, and its gate is connected to the input bus. The diode's anode is connected to the VCB supply line, and its cathode is grounded.

**FIGURE 3.3.1 Equivalent Circuit Around UT, VT, WT, UB, VB, WB Pins**

TABLE 3.3.1 List of Pins and Functions (2/2)

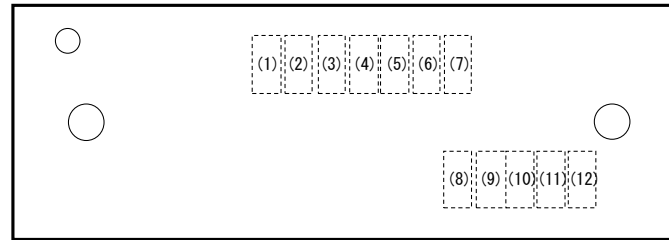
| No. | Pin | Pin functions                                                                                                                                  | Functions and Precautions                                                                                                                                                                                                                                                                                                                                                    | Related items                                                                                            | Remarks |
|-----|-----|------------------------------------------------------------------------------------------------------------------------------------------------|------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|----------------------------------------------------------------------------------------------------------|---------|
| 8   | RS  | Input for over-current protection                                                                                                              | <ul style="list-style-type: none"><li>Monitors the voltage of the shunt resistor Rs and detects over current status.</li></ul>                                                                                                                                                                                                                                               | <ul style="list-style-type: none"><li>3.5.1 (2)<br/>Setting method for over-current protection</li></ul> | —       |
|     |     |  <p><b>FIGURE 3.3.2 Equivalent Circuit Around RS Pin</b></p> |                                                                                                                                                                                                                                                                                                                                                                              |                                                                                                          |         |
| 9   | F   | Fault signal output                                                                                                                            | <ul style="list-style-type: none"><li>NMOS open drain output pin</li><li>The NMOS turns on only when the protection function operates, and in other cases, the NMOS is off.</li><li>Pull up to the CB pin or 5V through an external resistor RF. Moreover, to remove switching noise, connect the capacitor CF (0.01μF±10% recommended) between the F pin and GND.</li></ul> | <ul style="list-style-type: none"><li>3.5.1<br/>Protection function</li></ul>                            | —       |
|     |     |  <p><b>FIGURE 3.3.3 Equivalent Circuit Around F Pin</b></p>  |                                                                                                                                                                                                                                                                                                                                                                              |                                                                                                          |         |

### 3.4 Markings

Marks are indicated by laser marking on the following part:

SOP26, SOP26R, DIP26 : resin part of IC front side

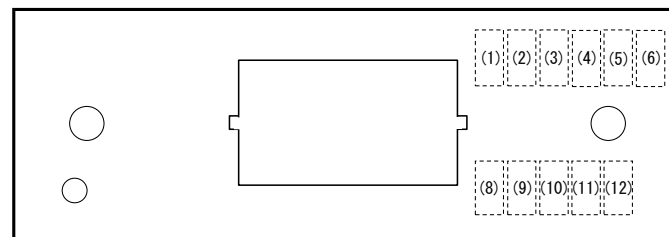
Side of Pin 1



Side of Pin 26

**FIGURE 3.4.1 SOP26 Marking Specifications**

Side of Pin 26



Side of Pin 1

**FIGURE 3.4.2 SOP26R, DIP26 Marking Specifications**

No. (1) to (7): Type name

No. (8) to (12): Lot number

The lot number consists of the followings.

No. (8): Last one-digit of the year of assembly

No. (9): Month of assembly:

January: A, February: B, March: C April: D, May: E, June: K,

July: L, August: M, September: N, October: X, November: Y, December: Z

No. (10) to (12): Quality control number

Represented with letters from "A" to "Z" except "I, O, and Q", numbers from "0" to "9", or blank.

### 3.5 Functions and Operational Precautions

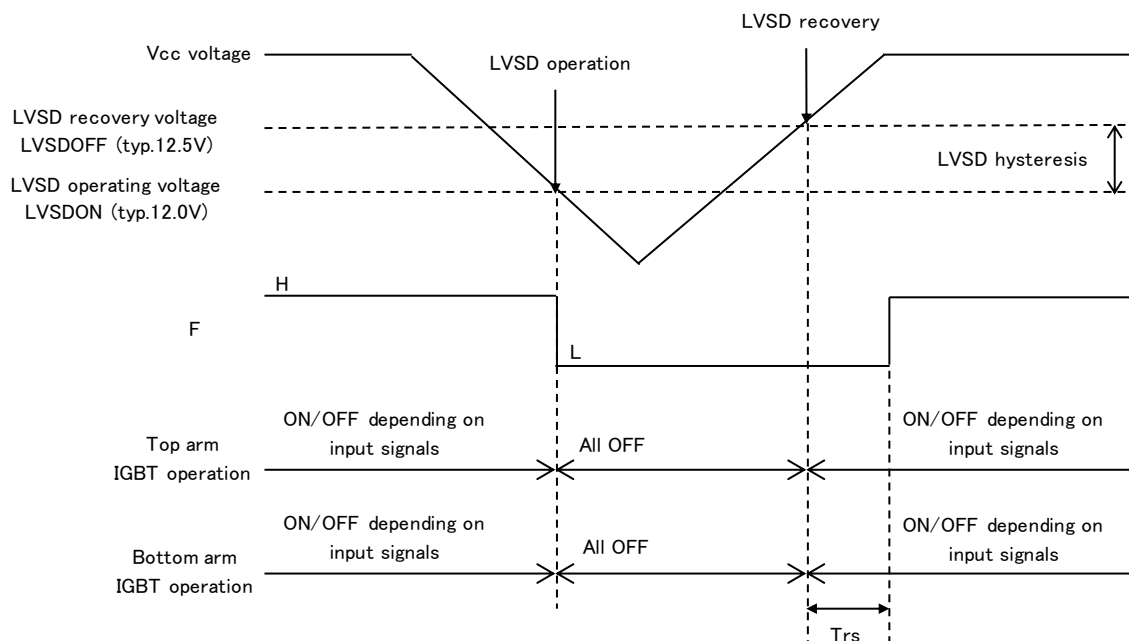
#### 3.5.1 Protection Function

##### (1) Vcc low-voltage detection

We call the Vcc low-voltage detection “LVSD”. When the Vcc voltage drops below the LVSD operating voltage (LVSDON, typ.12.0V), the F output is “L”, and all IGBTs (top and bottom arms) are turned off. When the Vcc voltage goes up to a level equal to or exceeding the LVSD recovery voltage (LVSDOFF, typ. 12.5V) and the protection recovery time (Trs) passes, the F output is “H”, and the IC automatically returns to a state in which the IGBTs operate depending on input signals. The protection recovery time is fixed at Trs.

FIGURE 3.5.1.1 shows the timing chart for the Vcc low-voltage detection operation.

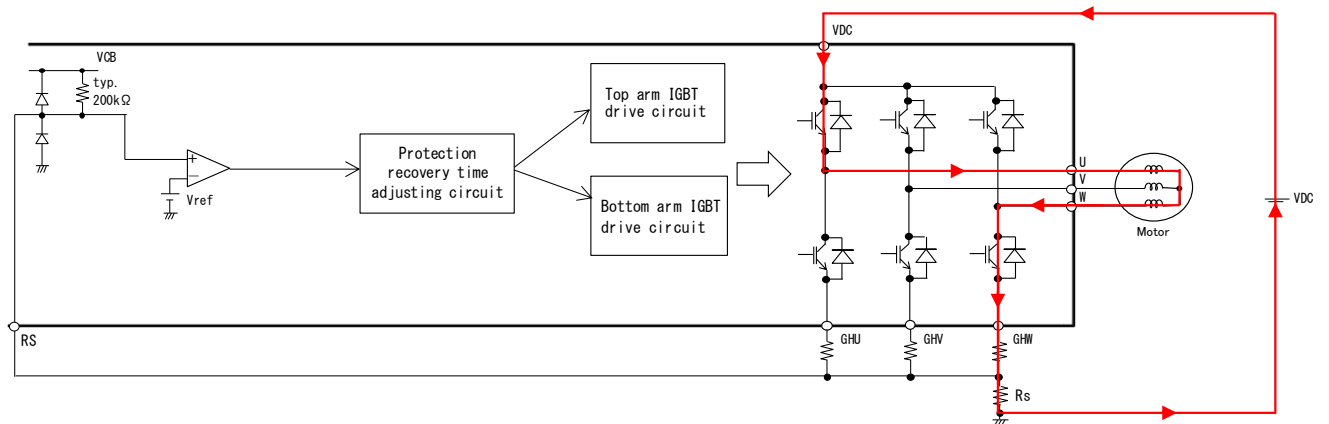
If the Vcc low-voltage detection operates during motor rotation, Vdc voltage may rise due to regenerative electric power to the Vdc power supply. The voltage at the VDC pin must not exceed the maximum rating. Particular attention is needed when the capacitance of a capacitor between the VDC and GND is small, because it makes the voltage more likely to rise.



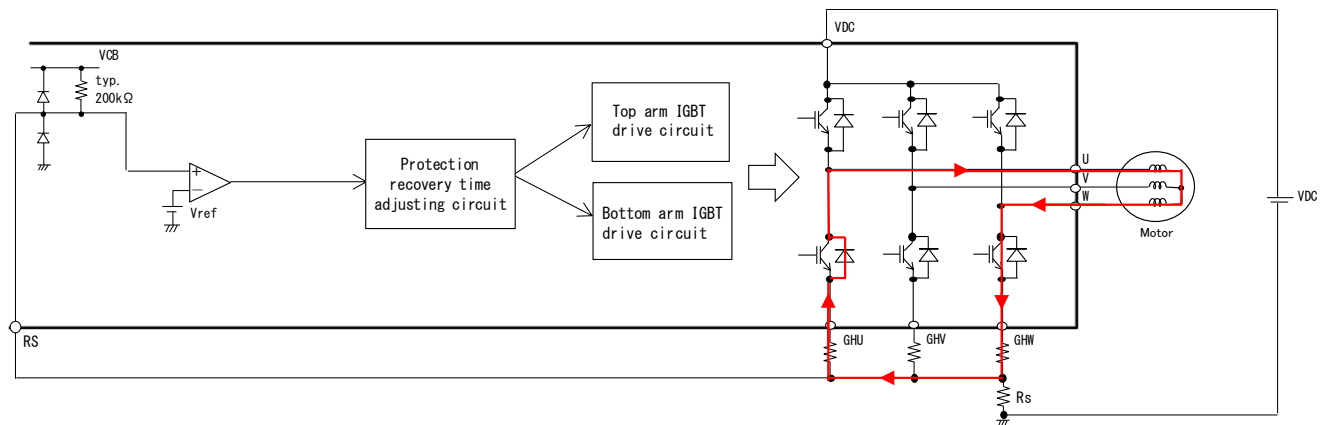
**FIGURE 3.5.1.1 Timing Chart for Vcc Low-voltage Detection Operation**

## (2) Setting method for over-current protection

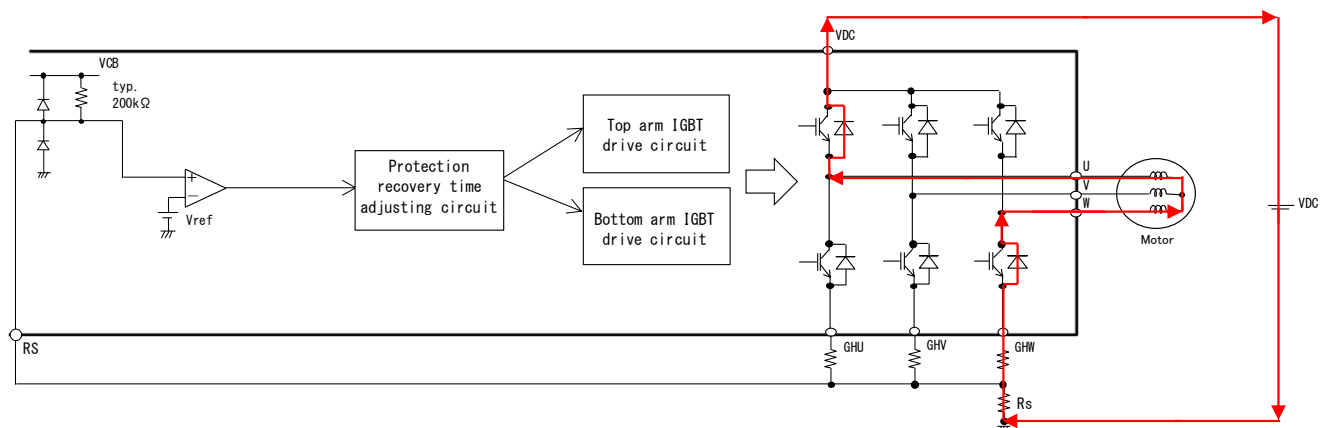
Figure 3.5.1.2 shows an example of the current flowing through the shunt resistor  $R_s$  when this function is enabled. This function is not effective for currents that do not flow forward (direction to the GL pin) through the shunt resistor, such as reflux current and power regenerative current (see Figures 3.5.1.3 and 3.5.1.4).



**FIGURE 3.5.1.2 Example of Current Path of Enabled Over-current Protection**



**FIGURE 3.5.1.3 Example of Reflux Current**

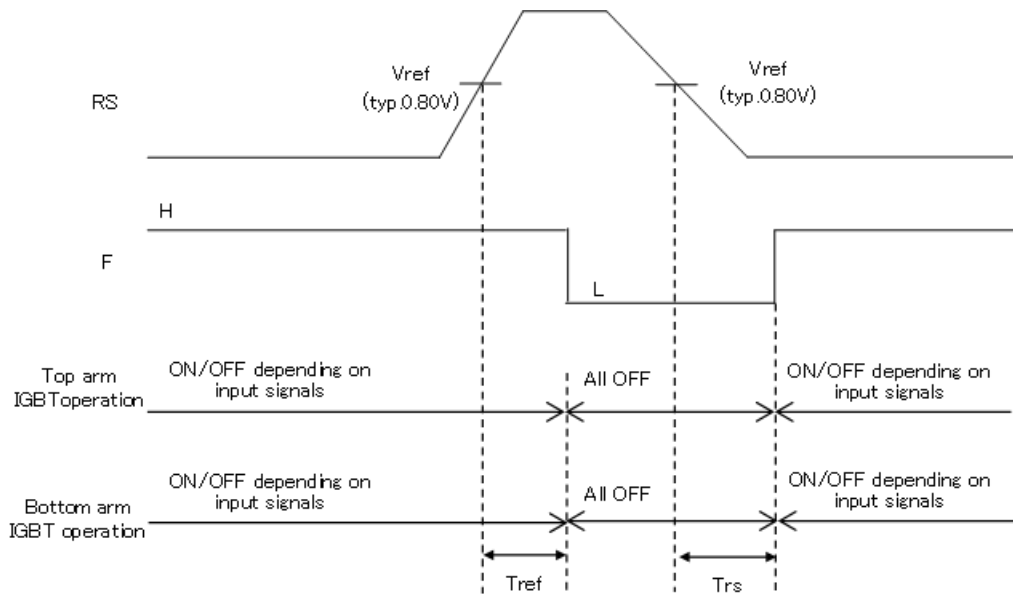


**FIGURE 3.5.1.4 Example of Power Regenerative Current**

## (a) Over-current protection

When the voltage at the RS pin reaches the over-current protection reference voltage ( $V_{ref}$ , typ. 0.80V), the F output is "L", and all IGBTs (top and bottom arms) are turned off. When the voltage at the RS pin drops below the over-current protection reference voltage ( $V_{ref}$ , typ. 0.80V) and the over-current protection recovery time passes, the F output is "H", and the IC automatically returns to a state in which the IGBTs operate depending on input signals. The protection recovery time is fixed at  $T_{rs}$ .

Figure 3.5.1.5 shows the timing chart for the over-current protection operation.



**FIGURE 3.5.1.5 Timing Chart for Over-current Protection Operation**

## (b) How to set current value of over-current protection

The over-current protection set value ( $I_O$ ) is calculated as follows:

$$I_O = V_{ref} / R_s$$

Where

$V_{ref}$ : Over-current protection reference voltage

$R_s$  : Shunt resistance value

In setting current values, delay time to turn the IGBT off ( $T_{ref}$ ),  $V_{ref}$  variability and  $R_s$  variability need to be considered. Observe the output currents of the IC (the coil currents of the motor) and confirm a design margin. Set the shunt resistance so that voltages of the GHU, GHV, and GHW pins are within the specified GH voltage ( $V_{gh}$ ) range in the Product Specification.

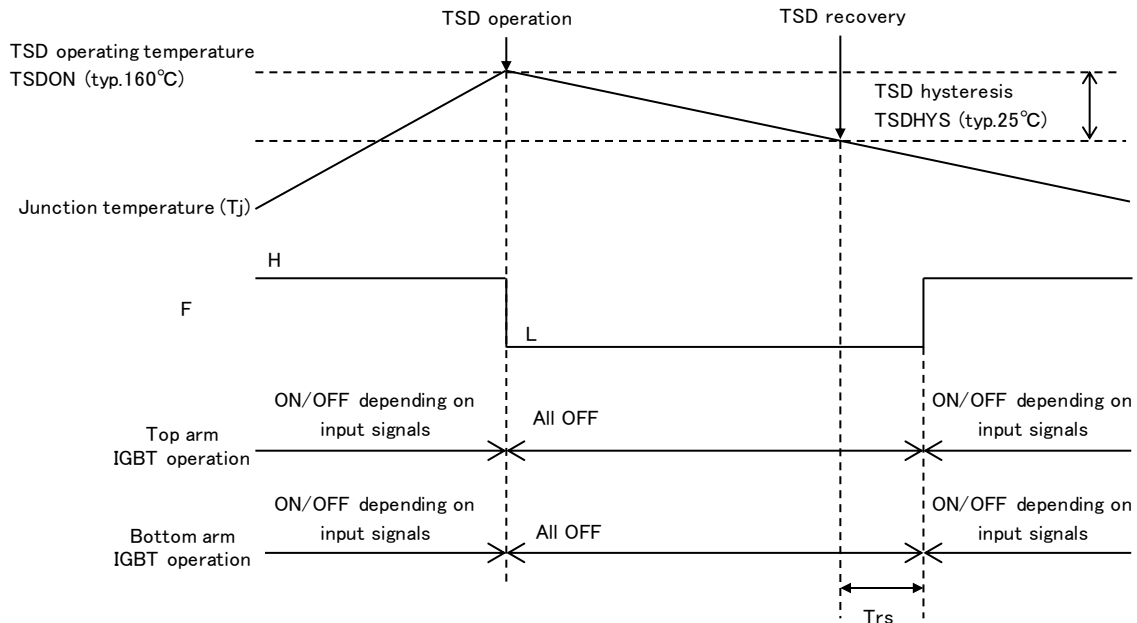
## (c) Wiring precautions

Make the wiring of the shunt resistor  $R_s$  as short as possible. The GHU, GHV and GHW are connected to the IGBT emitters. If the wiring has high resistance or high inductance component, the emitter potential of the IGBT changes, which can result in IGBT malfunction.

### (3) Over temperature protection

We call the Over temperature protection “TSD”. When the IC temperature exceeds the TSD operating temperature (TSDON, typ. 160°C), the F output is “L”, and all IGBTs (top and bottom arms) are turned off. When the IC temperature goes down the hysteresis (TSDHYS, typ. 25°C) from the TSD operating temperature (TSDON, typ. 160°C) and protection recovery time passes, the F output is “H”, and the IC automatically returns to a state in which the IGBTs operate depending on input signals. The protection recovery time is fixed at Trs.

Figure 3.5.1.6 shows the timing chart for the over temperature protection operation.



**FIGURE 3.5.1.6 Timing Chart for Over Temperature Protection Operation**

### (4) Short-circuit protection

If output of the inverter is short-circuited (load short-circuit, earth fault, and short-circuit between the top and bottom arms), there is a possibility that the IC will be destroyed. The over-current protection prevents damage to the IC due to load short-circuit and short-circuit between the top and bottom arms. However, in the case of earth fault whose current does not flow through the shunt resistor, the over-current protection does not operate because the IC cannot detect over-current. Thus, be sure to protect the device using external circuits of the IC in order to prevent damage caused when the IC cannot detect over-current such as an earth fault. Two or more occurrences of short-circuits can lead to the IC damage or failure because of local heat generated in the IGBTs. Proper precautions should be taken to prevent the over-current protection from operating repeatedly more than once caused by short-circuit.

### 3.5.2 New Bootstrap

The new bootstrap is a power supply method for the top arm that is characterized by charging the built-in capacitor in the IC from the Vdc power supply (high voltage power supply). A low PWM frequency lowers the charge voltage in the built-in capacitor, which could cause a higher voltage drop of the top arm output. As a guide, the PWM frequency should be 20 kHz ( $14 \text{ kHz} \leq f_{\text{PWM}} \leq 30 \text{ kHz}$  is recommended).

If the output ON-duty is high, a voltage drop of the top arm output may increase because the charging time of the built-in capacitor is insufficient. The output ON-duty ratio should be 98% or less.

When the Vdc power supply voltage is low, the built-in capacitor is not sufficiently charged. That could cause a higher voltage drop of the top arm output. The Vdc power supply voltage should be within the voltage range specified in the Product Specification.

### 3.5.3 Power On/Off Sequence

Sequence free in followings (1), (2), and (3).

- (1) Power-on sequence
- (2) Power-off sequence
- (3) Power-off and reset operation in instantaneous power failure occurrence

### 3.5.4 VCB Power Supply

The VCB power supply is generated from Vcc power supply and outputted from the CB pin. The VCB power is supplied to the IC internal circuits such as the over-current protection circuit. Figure 3.5.4.1 shows an equivalent circuit. This circuit constitutes a feedback circuit.

To prevent oscillation, connect capacitor C0 to the CB pin. The recommended capacitance for the C0 is  $1.0\mu\text{F} \pm 10\%$ . The larger the C0 capacity, the more stable the VCB power supply. However, excessive capacitance is not recommended. As a guide, it should be  $2\mu\text{F}$  to  $3\mu\text{F}$  or less.

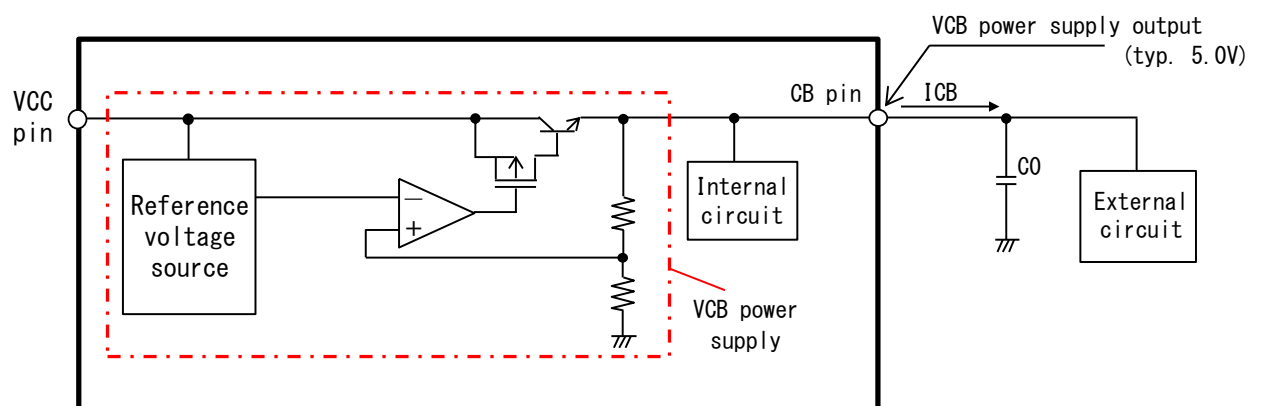
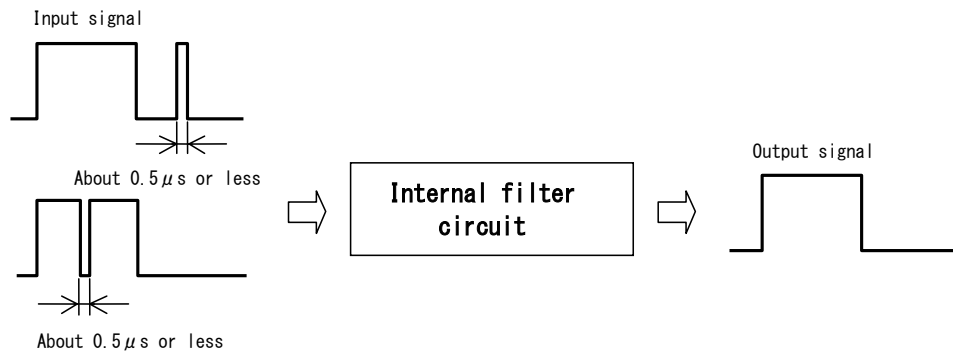


FIGURE 3.5.4.1 Equivalent Circuit for VCB Power Supply

### 3.5.5 Internal Filter Circuit

Internal filter circuits are located before the top and bottom arm drivers. The filter circuits remove signals and switching noise with widths less than about  $0.5\mu\text{s}$  inputted to the input pins (UT, VT, WT, UB, VB, WB).



**FIGURE 3.5.5.1 Operation of Internal Filter Circuit**

### 3.5.6 Derating

How much to derate a unit from the maximum rating is an important issue to consider for a reliable design. Items to be considered in the stage of system design include the derating of voltage, current, power, load, and electric stresses, along with the derating of temperature, humidity, other environmental conditions, vibration, impact, and other mechanical stresses.

Table 3.5.6.1 specifies the standard examples of derating to be considered when creating a reliable design. To consider these derating items in the equipment design stage is desirable for achieving reliability. If any item is difficult to be controlled within the standard, another means will be necessary, such as selecting a device having higher maximum ratings. Please consult our sales representative in advance.

**TABLE 3.5.6.1 Typical Derating Design Standards**

| Item                                 | Type                            |
|--------------------------------------|---------------------------------|
|                                      | ECN30626F, ECN30626R, ECN30626P |
| Junction temperature T <sub>j</sub>  | 110°C maximum                   |
| V <sub>dc</sub> power supply voltage | 450V maximum                    |
| Output peak current                  | 1.4A maximum                    |

## 3.6 Handling

### (1) Insulation between pins

High voltages are applied between the pin numbers specified below. Please apply coating resin or molding treatment as necessary.

- SOP26, SOP26R, DIP26: Between pin numbers: 4-5, 5-6, 6-7, 7-8

### (2) Connection of tabs

The tab and the GL pin of the IC are connected in the frame. Regarding the tab, take note of the following points.

#### (a) SOP26

Leave the tab unconnected or set the tab potential to the same as that of the GL pin.

The tab is placed on the IC lower surface (on PCB side). Wiring lines other than GND on the PCB must not touch the tab even if a coating such as solder resist is applied. Please secure sufficient insulation distance particularly between high voltage wiring lines and the tab.

#### (b) SOP26R, DIP26

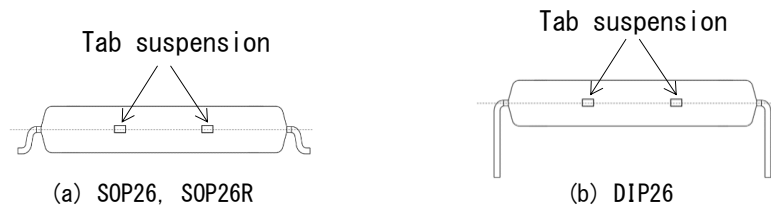
Leave the tab unconnected or set the tab potential to the same as that of the GL pin.

The tab is placed on the IC upper surface. If it is required to insulate between the IC tab and the housing, please insert an insulation sheet or something similar between them. If the insulation between the tab and the housing is insufficient, the IC will not be able to withstand an isolation withstand voltage test in which a high voltage is applied between the housing and the GND.

## (3) Tab suspension

Figure 3.6.1.1 shows a side view of the IC.

There are parts called “tab suspension” on both side surfaces of the IC. These tab suspensions are connected to the same potential as the GL pin. When the high voltage wire or/and components are laid out close to the tab suspensions, insulate them with coating, mold, or other treatment.



**FIGURE 3.6.1.1 Side Views of ICs**

## (4) Coating resin

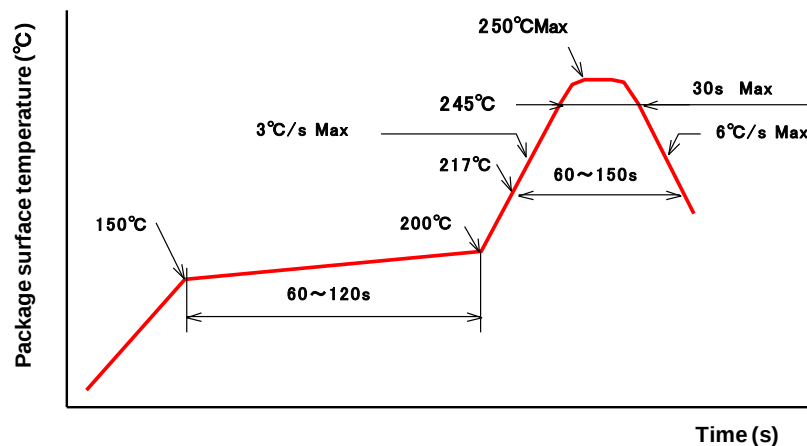
The influence of coating resin on semiconductor devices (thermal stress, mechanical stress and other stress) depends on PCB size, mounted components, etc. to be used. When selecting a coating resin, consult with your PCB manufacturer and resin manufacturer.

## (5) Soldering conditions

## (a) Soldering condition for SOP26, SOP26R

This IC is lead-free (Pb-free). The recommended reflow soldering condition is shown in Figure 3.6.1.2.

If attaching a heat sink to SOP26R, do not solder to the tab. The solder on the tab impairs the tab flatness, which causes poor contact with the heat sink mounting surface. As a result, the heat dissipation may decrease.



**FIGURE 3.6.1.2 Recommended Conditions for Infrared Reflow or Air Reflow**

## (b) Soldering condition for DIP26

The peak temperature of flow soldering\* must be 260°C or less, and the dip time must be within 10 seconds. High stress by mounting, such as long time thermal stress by preheating, mechanical stress, etc., can lead to degradation or destruction. Make sure that your mounting method does not cause problem as a system.

If attaching a heat sink, do not solder to the tab. The solder on the tab impairs the tab flatness, which causes poor contact with the heat sink mounting surface. As a result, the heat dissipation may decrease.

※ Flow soldering: Only pins enter a solder bath, while the resin or tab does not.

## (6) Solder joint reliability

Reliability of solder joints is influenced by soldering conditions, PCB material and foot patterns. Perform adequate evaluations on thermal cycle tests, heat shock tests, and other tests after mounting the IC on a PCB. Special care should be taken if the SOP26, SOP26R is mounted on a PCB having a high coefficient of thermal expansion (such as CEM-3) because the solder joint life could be shortened.

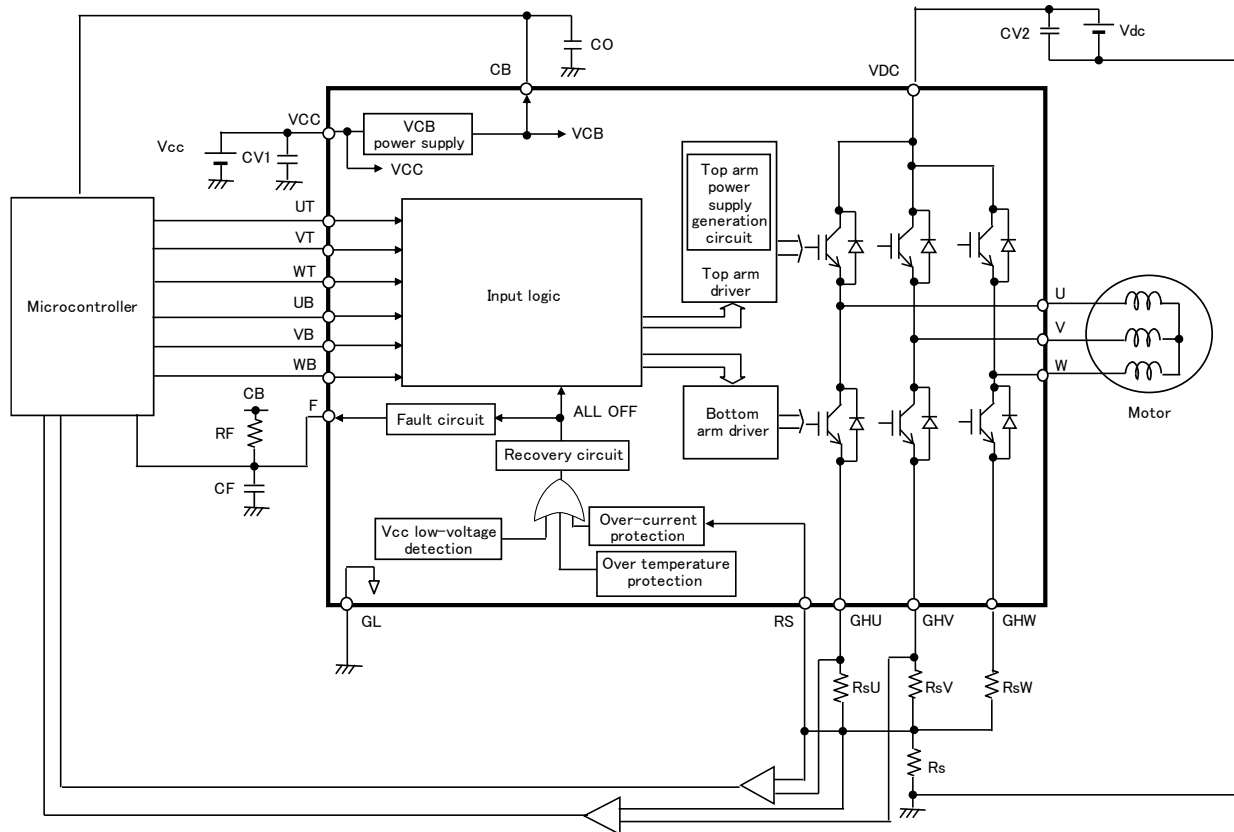
#### 4. Recommended Circuit

##### 4.1 External Components

Table 4.1.1 shows recommended external components.

**TABLE 4.1.1 External Components**

| Component | Standard value                  | Usage                                   | Remarks                   |
|-----------|---------------------------------|-----------------------------------------|---------------------------|
| C0        | $1\mu\text{F}\pm 10\%$ , 25V    | Smooths the internal power supply (VCB) |                           |
| CV1       | $1\mu\text{F}\pm 10\%$ , 25V    | Smooths the Vcc power supply            | Note 1                    |
| CV2       | $33\text{nF}\pm 10\%$ , 630V    | Smooths the Vdc power supply            | Note 1                    |
| Rs        | $1\Omega\pm 1\%$ , 1W           | Sets over-current protection            | Note 2 for how to set Rs. |
| CF        | $0.01\mu\text{F}\pm 10\%$ , 25V | Eliminates output noise of Fault signal |                           |
| RF        | $10\text{k}\Omega\pm 10\%$      | For pull up                             |                           |



**FIGURE 4.1.1 Block Diagram and External Components of IC**

Note 1. Caution for smoothing capacitor

As necessary, increase the capacitance and add a zener diode in consideration of noise immunity. Mount each of the components close to the pins of the IC.

Note 2. Section 3.5.1 (2) (b) shows how to set the resistance value.

#### 4.2 Other External Components

It is recommended to mount the components shown in Table 4.2.1 to stabilize the power supply and protect the IC from voltage surge.

Adjust the settings of components in accordance with the conditions of use. Moreover, mount each of the components close to the pins of the IC to achieve the effect of the voltage surge absorption.

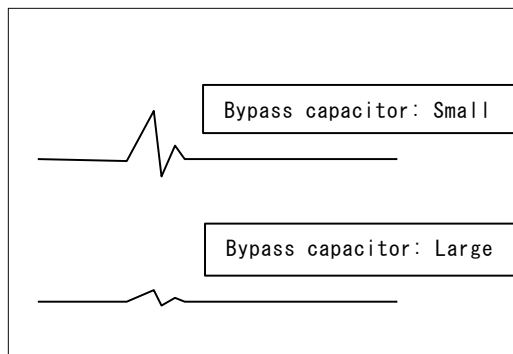
**TABLE 4.2.1 Other External Components**

| No. | Components | Purpose                                   | Remarks                                                              |
|-----|------------|-------------------------------------------|----------------------------------------------------------------------|
| 1   | Cvcc1      | for VCC. To suppress high frequency noise | Ceramic capacitor with good frequency response, etc. About 1 $\mu$ F |
| 2   | Cvcc2      | for VCC. To smooth Vcc power supply       | Electrolytic capacitor, etc. About 1 $\mu$ F                         |
| 3   | ZDvcc      | for VCC. To suppress over voltage         | Zener diode with good frequency response                             |
| 4   | Cvdc1      | for VDC. To suppress high frequency noise | Ceramic capacitor with good frequency response, etc. About 33nF/630V |
| 5   | Cvdc2      | for VDC. To smooth Vdc power supply       | Electrolytic capacitor, etc. About 1 $\mu$ F/630V                    |

## 5. Failure Examples (Assumptions)

### 5.1 Inverter IC Destruction by External Surge Inputted to Vdc and Vcc Lines (Case 1)

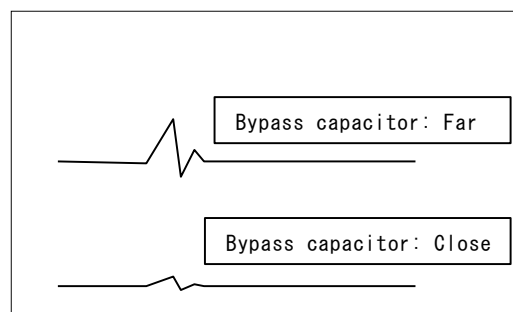
- Cause : An external surge entered the IC on the Vdc and Vcc lines of the motor. Because the capacitance of the bypass capacitor for surge suppression was small, the surge could not be sufficiently suppressed.
- Phenomenon : The motor does not rotate due to the over-voltage destruction of the IC.
- Countermeasure : Use the bypass capacitor for surge suppression; its capacity should be enough to suppress surges.



**FIGURE 5.1.1 Example of Surge Waveforms for Different Capacitance of Bypass Capacitor**

### 5.2 Inverter IC Destruction by External Surge Inputted to Vdc and Vcc Lines (Case 2)

- Cause : An external surge entered the IC on the Vdc and Vcc lines of the motor. Because the external components for surge suppression were positioned far from the IC on the circuit board, the surge could not be sufficiently suppressed.
- Phenomenon : The motor does not rotate due to the over-voltage destruction of the IC.
- Countermeasure : The bypass capacitor and Zener diode for surge suppression should be mounted close to the IC.



**FIGURE 5.2.1 Example of Surge Waveform for Different Bypass Capacitor Locations on the Board**

### 5.3 Inverter IC Destruction by External Surge Inputted to Vdc and Vcc Lines (Case 3)

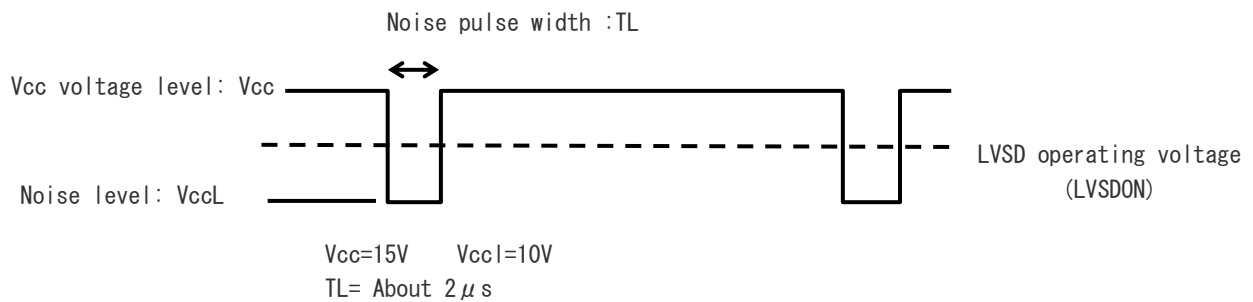
- Cause : When a power supply line was in an open state due to the connector contact failure of the Vdc and Vcc line or the like, the supply power was turned on. Then, when the power supply line went into a closed state, an external surge occurred and entered the IC.
- Phenomenon : The motor does not rotate due to the over-voltage destruction of the IC.
- Countermeasure : The Zener diode for surge suppression should be mounted close to the IC.

### 5.4 Inverter IC Destruction by External Surge Inputted to Vdc and Vcc Lines (Case 4)

- Cause : An external surge entered the IC on the Vdc and Vcc lines of the motor. Because the Zener voltage of the surge suppressor diode was higher than the maximum rating voltage of the IC, it did not protect the IC.
- Phenomenon : The motor does not rotate due to the over-voltage destruction of the IC.
- Countermeasure: Use a surge suppressor diode with Zener voltage which is lower than the maximum rating voltage of the IC. The larger the rating capacity of the Zener diode, the more effectively the surge suppressor works.

### 5.5 Inverter IC Destruction by External Surge Inputted to Vcc Line

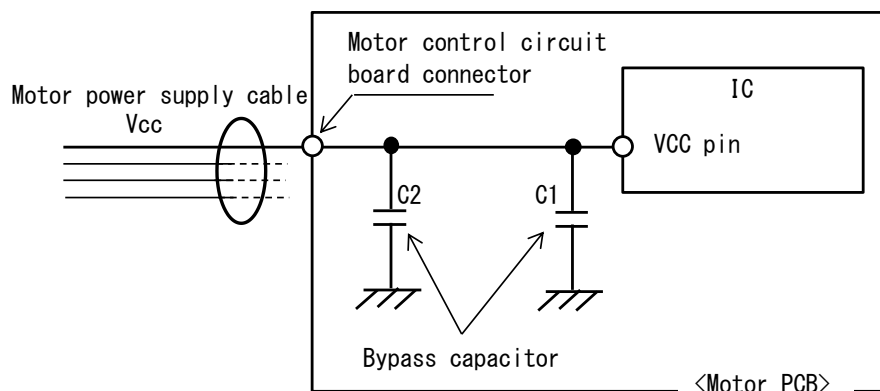
- Cause : Pulsed noise of a voltage that was lower than the LVSD operating voltage (LVSDON) entered the Vcc line. In this case, the IC repeats split-second protection function operation. Then the IC has the possibility of overheat breakage.
- Phenomenon : The motor does not rotate due to the destruction of the IC.
- Countermeasure: ① Remove the noise that enters the motor Vcc line by reviewing the power supply circuit (inductance of power cable, noise filter circuit or the like).  
② Connect a capacitor having sufficient capacitance close to the VCC pin and GL pin of the IC to absorb noise.



**FIGURE 5.5.1 Example of Pulsed Noise on Vcc Line**

### 5.6 Inverter IC Destruction by Vcc Line Noise

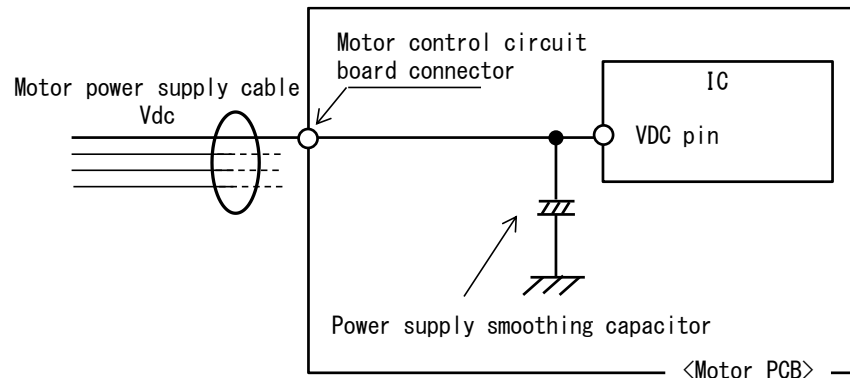
- Cause : Surge voltage that exceeded the maximum rating for the IC entered the VCC pin.
- Phenomenon : The motor does not rotate due to the over-voltage destruction of the IC.
- Countermeasure:
  - ① Mount a bypass capacitor C1 near the pin of the IC. Use a capacitor that has excellent frequency characteristics, such as a ceramic capacitor. As a guide, a capacitor of around 1μF is recommended.
  - ② It is more effective to mount a surge suppression device, such as bypass capacitor C2 shown in Figure 5.6.1, close to the connector of a motor control circuit board.



**FIGURE 5.6.1 Example of Mounted Surge Suppression Devices**

### 5.7 Inverter IC Destruction by Noise at Vdc Power Supply Power-on

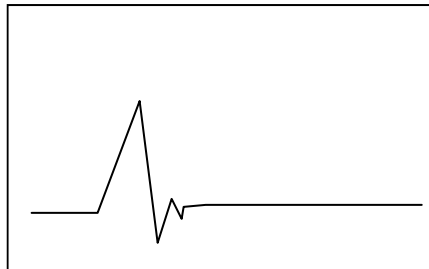
- Cause : Surge voltage that exceeded the maximum rating for the IC entered the VDC pin because the voltage rose suddenly when the Vdc power supply was powered on.
- Phenomenon : The motor does not rotate due to the over-voltage destruction of the IC.
- Countermeasure : Mount a power supply smoothing capacitor near the VDC pin of the IC. An electrolytic capacitor is generally used as a power supply smoothing capacitor.



**FIGURE 5.7.1 Example of Mounted Power Supply Smoothing Capacitor**

### 5.8 Inverter IC Destruction by Inspection Machine Relay Noise

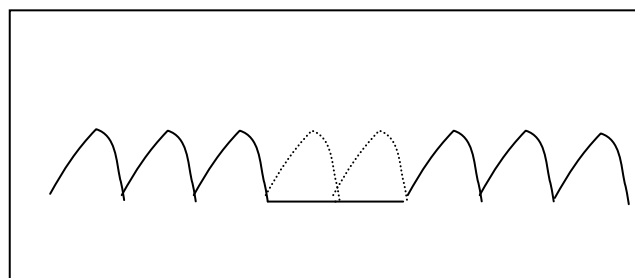
- Cause : A mechanical relay for on-off control of the electric connection between the IC and an inspection machine generated a surge that entered the IC.
- Phenomenon : The motor does not rotate due to the over-voltage destruction of the IC.
- Countermeasure : Use a semiconductor relay, etc. Confirm a surge generated when the relay is on-off is less than the maximum rated value.



**FIGURE 5.8.1 Example of Surge Waveform When Mechanical Relay is Used**

### 5.9 Motor Failure (Missing Phase Output)

- Cause : The motor with missing phase has been out on the market.
- Phenomenon : The motor might start depending on the rotor position when starting even if the motor has missing phase output. Therefore, the missing phase output of motor cannot be detected by the motor rotation test.
- Countermeasure: Monitor the motor current or oscillation in order to detect the missing phase output of motor.



**FIGURE 5.9.1 Example of Motor Current Waveform in Phase Missing Condition**

## 6. Precautions for Use

In this document, "MPSD" stands for Minebea Power Semiconductor Device Inc.

### 6.1 Countermeasures against Electrostatic Discharge (ESD)

- (a) Customers need to take precautions to protect ICs from electrostatic discharge (ESD). The material of the container or any other device used to carry ICs should be free from ESD, which can be caused by vibration during transportation. Use of electrically conductive containers is recommended as an effective countermeasure.
- (b) Everything that touches ICs, such as the work platform, machine, measuring equipment, and test equipment, should be grounded.
- (c) Workers should be high-impedance grounded (100kΩ to 1MΩ) while working with ICs, to avoid damaging the ICs by ESD.
- (d) Friction with other materials, such as high polymers, should be avoided.
- (e) When carrying a PCB with a mounted IC, ensure that the electric potential is maintained at a constant level using the short-circuit terminals and that there is no vibration or friction.
- (f) The humidity at an assembly line where ICs are mounted on circuit boards should be kept around 45 to 75 percent using humidifiers or such. If the humidity cannot be controlled effectively, using ionized air blowers (ionizers) is effective.

### 6.2 Storage Conditions (applied to: ECN30626F, ECN30626R)

- (1) Before opening the moisture prevention bag (aluminum laminate bag)

Temperature: less than 40°C

Humidity: less than 90%RH

Period: less than 12 months

- (2) After opening the moisture prevention bag (aluminum laminate bag)

Temperature: 5°C to 30°C

Humidity: less than 60%RH

Period: less than 168 hours

※ When the period of (1) and (2) is likely to expire, store ICs in a drying furnace (10%RH or lower) at ordinary temperature.

- (3) Baking process

When the period of (1) and (2) has expired, ICs should be baked in accordance with the following conditions. (However, when ICs are stored in a drying furnace (10%RH or lower) at ordinary temperature, there is no need to bake.)

Do not bake the tape and the reel of the taping package because they are not heat resistant.

Transfer ICs to a heat resistant container prior to baking.

Temperature: 125°C to 135°C

Period: more than 48 hours

### 6.3 Maximum Ratings

Regardless of changes in external conditions during use of the MPSD IC, the "maximum ratings" should never be exceeded when designing electronic circuits that employ the MPSD IC. If maximum ratings are exceeded, the MPSD IC may be damaged or destroyed. In no event shall MPSD be liable for any failure in the MPSD IC or any secondary damage resulting from use at a value exceeding the maximum ratings.

### 6.4 Derating Design

Continuous high-load operation (high temperatures, high voltages, large currents) should be avoided and derating design should be applied, even within the ranges of the maximum ratings, to ensure reliability.

### 6.5 Safe Design

The MPSD IC may fail due to accidents or unexpected surge voltages. Accordingly, adopt safe design features, such as redundancy and measures to prevent misuse, in order to avoid extensive damage in the event of a failure.

### 6.6 Application

If the MPSD IC is applied to the following uses where high reliability is required, obtain the document of permission from MPSD in advance.

- Automobile, Train, Vessel, etc.

Do not apply the MPSD IC to the following uses where extremely high reliability is required.

- Nuclear power control system, Aerospace instrument, Life-support-related medical equipment, etc.

## 7. Notes Regarding this Document

- (1) All information included in this document such as product data, diagrams, charts, algorithms, and application circuit examples, is current as of the date this document is issued. Such information, specifications of products, etc. are subject to change without prior notice. Before purchasing or using any of the MPSD products listed in this document, please confirm the latest product information with a MPSD sales office.
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